Multilayer Ceramic Chip Capacitors
CGA3E2C0G1H100D080AA

TDK item description CGA3E2C0G1H100DT****

| Applications | Automotive Grade |
| :--- | :--- | :--- |
| Feature | General General (Up to 50V) |
|  | AEC-Q200AEC-Q200 |
| Series | CGA3(1608) [EIA 0603] |
| Status | Production |



Dimensions inmm

|  | Size |
| :--- | :--- |
| Length(L) | $1.60 \mathrm{~mm} \pm 0.10 \mathrm{~mm}$ |
| Width(W) | $0.80 \mathrm{~mm} \pm 0.10 \mathrm{~mm}$ |
| Thickness(T) | $0.80 \mathrm{~mm} \pm 0.10 \mathrm{~mm}$ |
| Terminal Width(B) | 0.20 mm Min. |
| Terminal Spacing(G) | 0.30 mm Min. |
| Recommended Land Pattern (PA) | 0.70 mm to 1.00 mm (Flow Soldering) |
| Recommended Land Pattern (PB) | 0.60 mm to 0.80 mm (Reflow Soldering) |
| Recommended Land Pattern (PC) | 0.80 mm to 1.00 mm (Flow Soldering) |
|  | 0.60 mm to 0.80 mm (Reflow Soldering) |


|  | Electrical Characteristics |
| :--- | :--- |
| Capacitance | $10 \mathrm{pF} \pm 0.5 \mathrm{pF}$ |
| Rated Voltage | 50 VDC |
| Temperature Characteristic | $\mathrm{COG}\left(0 \pm 30 \mathrm{ppm} /{ }^{\circ} \mathrm{C}\right)$ |
| Q (Min.) | 600 |
| Insulation Resistance (Min.) | $10000 \mathrm{M} \Omega$ |


|  | Other |
| :--- | :--- |
| Soldering Method | Wave (Flow) |
| AEC-Q200 | Reflow |
| Packing | Yes |
| Package Quantity | Punched (Paper)Taping  Reel] |

[^0]Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)





[^1]
## Associated Images




[^0]:    ! Images are for reference only and show exemplary products.
    ! This PDF document was created based on the data listed on the TDK Corporation website,
    ! All specifications are subject to change without notice.

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